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NOV 14 2006

Application No.: 10/810,436

Docket No.: JCLA12013

**REMARKS****Present Status of the Application**

Claims 1-23 are pending and claims 2 and 9-23 are withdraw of which claim 1 have been amended to more clearly describe the claimed invention. Therefore, it is believed that no new matter adds by way of amendment to claims or otherwise to the application.

Applicants respectfully submit that at least for the following reasons claims 1 and 3-8 patently define over prior arts of record. Reconsideration is respectfully requested.

**Claim Rejections – 35 USC 112, Second Paragraph**

Applicants have amended claim 8. In claim 8, the phrase “on one side outside of said rectangle” has been amended to read as “on one side of said rectangle”.

Withdrawal of the rejection is requested.

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**Discussion of the claim rejection under 35 USC 102**

*Applicants respectfully traverse the 102(e) rejection of claims 1 and 3-7 because Meckes et al. (U.S. 7,061,098, hereinafter Meckes) does not teach every element recited in these claims.*

The present invention is in general related a chip package as claim 1 recites:

1. A chip package, comprising:
  - a chip, having an active surface and a plurality of bond pads, said bond pads being on said active surface; and
  - a rigid cover, on said active surface, said rigid cover exposing said plurality of bond pads above said active surface; and
  - an adhesive layer, disposed between the chip and the rigid cover, and the rigid cover is adhered to the chip via the adhesive layer.

Meckes fails to disclose, teach or suggest that the feature of "an adhesive layer, disposed between the chip and the rigid cover, and the rigid cover is adhered to the chip via the adhesive layer". In the Meckes reference, the method for forming the self-supporting electrically conductive cover layer includes fellow steps. As shown in Fig. 2, a sacrificial layer 21 is formed on the semiconductor die 2. Then, as shown in Fig. 3, a self-supporting electrically conductive cover layer 9 is formed on the sacrificial layer 21. Next, as shown in Fig. 4, the sacrificial layer 21 is removed. In brief, the Meckes discloses that "the cover layer 9 was formed in an organometallic gas phase reactor in which a heavily doped polycrystalline silicon with a thickness of between about 0.3 .mu.m and about 10 .mu.m is deposited on the sacrificial layer 21 and in the openings 22 [column 6, lines 34-38]." Therefore, the cover layer 9 is fixed on the semiconductor die 2 without an adhesive layer in the Meckes. But, the rigid cover is fixed on the chip with an adhesive layer in the present application.

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Therefore, Meckes fails to disclose that an adhesive layer disposed between the chip and the rigid cover, and the rigid cover is adhered to the chip via the adhesive layer. Meckes does not teach every element recited in the amended proposed claim 1.

For at least the foregoing reasons, Applicant respectfully submits that amended proposed independent claim 1 is not anticipated by Meckes, and should be allowed. For at least the same reasons, dependent claims 3-7 are not anticipated either.

**Discussion of the claim rejection under 35 USC 103**

*Applicants respectfully traverse the rejection of claim 8 under 103(a) as being anticipated over Meckes et al. (U.S. 7,061,098, hereinafter Meckes) in view of Nishiguchi et al. (JP404024928A, hereinafter Nishiguchi) because a prima facie case of obviousness has not been established by the Office Action.*

To establish a prima facie case of obviousness under 35 U.S.C. 103(a), each of three requirements must be met. First, the reference or references, taken alone or combined, must teach or suggest each and every element in the claims. Second, there must be some suggestion or motivation, either in the references themselves or in the knowledge generally available to one of ordinary skill in the art, to combine the references in a manner resulting in the claimed invention. Third, a reasonable expectation of success must exist. Moreover, each of the three requirements must "be found in the prior art, and not be based on applicant's disclosure." See M.P.E.P. 2143, 8th ed., February 2003.

Applicants would like to particularly point out that the publication number of Nishiguchi provided by the Examiner is wrong, and the publication number of Nishiguchi should be JP0424928.

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Applicants respectfully submit that the amended proposed independent claim 1 is allowable over Meckes in view of Nishiguchi because Meckes and Nishiguchi substantially fails to teach, suggest or disclose every elements of the claimed invention as claimed in the amended proposed independent claim 1. Applicants would like to particularly point out that Meckes fails to disclose that an adhesive layer disposed between the chip and the rigid cover, and the rigid cover is adhered to the chip via the adhesive layer. Therefore, the differences between amended claim 1 of the present invention and Meckes and Nishiguchi would not have been obvious at the time the invention was made to a person having ordinary skill in the art.

Claims 3-8, which directly or indirectly depend from the amended proposed independent claims 1 are also patentable over Meckes in view of Nishiguchi at least because of their dependency from an allowable base claim.

For at least the foregoing reasons, Applicants respectfully submit that claims 1, and 3-8 patentably define over Meckes in view of Nishiguchi. Reconsideration and withdrawal of above rejections is respectfully requested.

#### Discussion of Election/Restrictions

If the amended proposed independent claims 1 is allowed, upon the allowance of a generic claim, applicant will be entitled to consideration of claims to additional species which are written in dependent form or otherwise include all of the limitations of an allowed generic claim as provided by 37 CFR 1.141.

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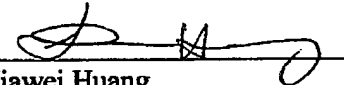
CONCLUSION

For at least the foregoing reasons, it is believed that claims 1 and 3-8 of the present application patentably define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date: 11/14/2006

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